

Schematic Key for Multilayer and HDI-Technology Build-Ups

a	b	c	d	e	f	g + h + i
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06 216 FR4 35 L20.35_41.105 P10 S1

columns and equal kind of positions are separated by "_". Equal prefixes in one column are reduced to one.

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Layers	in μ	Material	Build-Up	Assembly
Layer-1	35 μ	Copper		A1
	100 μ	Prepreg		
	100 μ	Prepreg		
	200 μ	L-FR4		
Layer-2	35 μ	Copper		A2
	100 μ	Prepreg		
	100 μ	Prepreg		
	100 μ	Prepreg		
Layer-3	105 μ	Copper		A3
	410 μ	L-FR4		
Layer-4	105 μ	Copper		A4
	100 μ	Prepreg		
	100 μ	Prepreg		
	100 μ	Prepreg		
Layer-5	35 μ	Copper		A5
	200 μ	L-FR4		
	100 μ	Prepreg		
	100 μ	Prepreg		
Layer-99	35 μ	Copper		B

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